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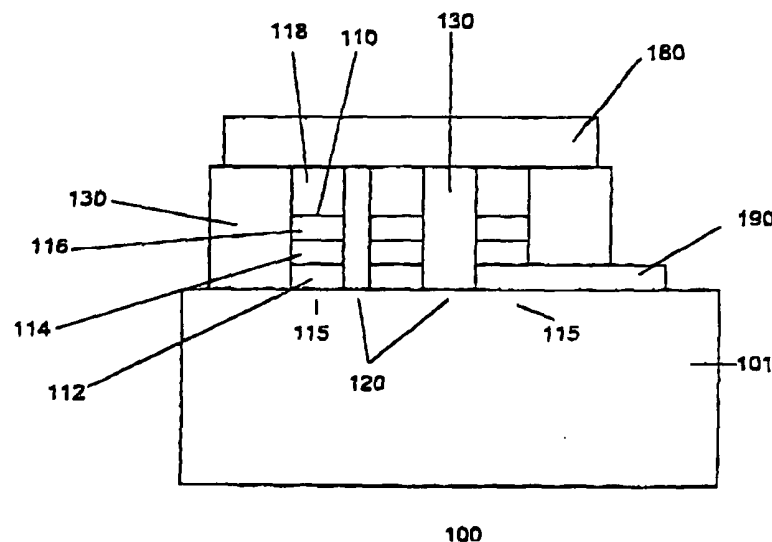
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- (71) Applicant (for all designated States except US): OSRAM OPTO SEMICONDUCTORS GMBH & CO. OHG [DE/DE]; Wernerwerksstrasse 2, D-93049 Regensburg (DE).
- (72) Inventor; and
- (75) Inventor/Applicant (for US only): GUENTHER, Ewald, Karl, Michael [DE/SG]; 991 Bukit Timah Road #03-11, Maplewoods, Singapore 589630 (SG).
- (74) Agent: EPPING, Wilhelm; Epping Hermann & Fischer GbR, Postfach 12 10 26, D-80034 München (DE).
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(54) Title: ENCAPSULATION OF A DEVICE



(57) Abstract: An encapsulation for an electrical device (100) is disclosed. A cap support (130) is provided in the non-active regions (120) of the device (100) to prevent the package from contacting the active components (110) of the device due to mechanical stress induced in the package.

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Abstract

An encapsulation for an electrical device is disclosed. A cap support is provided in the non-active regions of the device to prevent the package from
5 contacting the active components of the device due to mechanical stress induced in the package.